

at least one dressing unit is a dressing unit comprising a dresser having a size larger than a diameter of said workpiece to be polished; and

at least one dressing unit is a dressing unit comprising a dresser having a size smaller than said diameter of said workpiece to be polished.

A2 4. (Amended) A dressing method for dressing a polishing surface provided in a polishing apparatus, wherein:

Reads on body used together with dressing process
initially conditioning said polishing surface before use in the polishing, by a dressing unit comprising a diamond dresser or an SiC dresser; and

conditioning said polishing surface between processes of polishing said workpiece to be polished, by a dressing unit comprising a brush dresser.

5. (Amended) A dressing method for dressing a polishing surface provided in a polishing apparatus, wherein:

initially conditioning said polishing surface before use in the polishing, by a dressing unit comprising a diamond dresser or an SiC dresser; and

between processes of polishing said workpiece to be polished, firstly conditioning said polishing surface by a dressing unit comprising a diamond dresser or an SiC dresser, and then conditioning said polishing surface by a dressing unit comprising a brush dresser.

6. (Amended) A dressing method for dressing during polishing of a workpiece to be polished in a polishing apparatus, wherein:

dressing is performed while moving a dressing unit comprising a dresser having a size smaller than a diameter of said workpiece to be polished; and

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after polishing operation is finished, dressing is performed by a dressing unit comprising a dresser having a diameter larger than said workpiece to be polished.

Please add the following new claims:

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--17. A polishing apparatus for polishing a workpiece, comprising:
a table for providing a polishing surface;
a first dresser having a contact surface for contacting said polishing surface during dressing operation;
a second dresser having a contact surface for contacting said polishing surface during dressing operation; and
an atomizer for spraying a fluid on said polishing surface to remove a polishing waste on said polishing surface.

18. A polishing apparatus for polishing a workpiece, comprising:
a table for providing a polishing surface;
a first dresser having a contact surface for contacting said polishing surface during dressing operation;
a second dresser having a contact surface for contacting said polishing surface during dressing operation;
a sensor for measuring a profile of said polishing surface; and
a controller for controlling a dressing process of said first dresser.

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19. A polishing apparatus according to claim 3, wherein dressers in said at least two dressing units comprise a ring shaped dresser or a disk shaped dresser.--